MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA

T-52-30-07

MC54/74HCT245

Octal 3-State Noninverting Bus Transceiver with LSTTL-Compatible Inputs

High-Performance Silicon-Gate CMOS

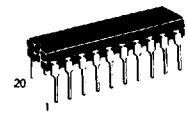
The MC54/74HCT245 may be used as a level converter for interfacing TTL or NMOS outputs to High-Speed CMOS inputs.

The HCT245 is identical in pinout to the LS245.

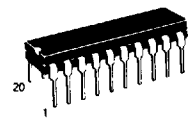
The HCT245 is a 3-state noninverting transceiver that is used for 2-way asynchronous communication between data buses. The device has an active-low Output Enable pin, which is used to place the I/O ports into high-impedance states. The Direction control determines whether data flows from A to B or from B to A.

The HCT245 performs functions similar to those of the HCT640 and the HCT643.

- Output Drive Capability: 15 LSTTL Loads
- TTL/NMOS-Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1 μA
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 304 FETs or 76 Equivalent Gates



J SUFFIX
CERAMIC
CASE 732-03



N SUFFIX
PLASTIC
CASE 738-03

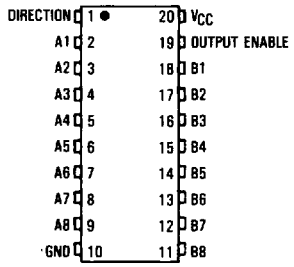
DW SUFFIX
SOIC
CASE 751D-03

ORDERING INFORMATION

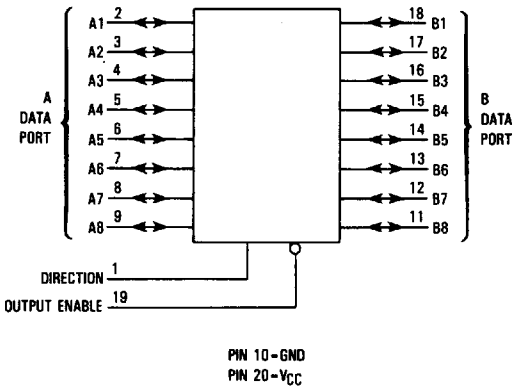
MC74HCTXXXN	Plastic
MC54HCTXXXJ	Ceramic
MC74HCTXXXDW	SOIC

T_A = −55° to 125°C for all packages.
Dimensions in Chapter 6.

PIN ASSIGNMENT



LOGIC DIAGRAM



PIN 10 = GND
PIN 20 = V_{CC}

FUNCTION TABLE

Control Inputs		
Output Enable	Direction	Operation
L	L	Data Transmitted from Bus B to Bus A
L	H	Data Transmitted from Bus A to Bus B
H	X	Buses Isolated (High-Impedance State)

X = don't care

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MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	−0.5 to +7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	−1.5 to V_{CC}+1.5	V
$V_{I/O}$	DC I/O Voltage (Referenced to GND)	−0.5 to V_{CC}+0.5	V
I_{in}	DC Input Current, per Pin 1 or 19	±20	mA
$I_{I/O}$	DC I/O Current, per I/O Pin	±35	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±75	mA
P_D	Power Dissipation in Still Air, Plastic or Ceramic DIP†	750	mW
	SOIC Package†	500	
T_{stg}	Storage Temperature	−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		°C
	(Plastic DIP or SOIC Package)	260	
	(Ceramic DIP)	300	

*Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: −10 mW/°C from 65° to 125°C
Ceramic DIP: −10 mW/°C from 100° to 125°C
SOIC Package: −7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 4.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltages higher than the maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic level (e.g., either GND or V_{CC}). Unused outputs must be left open. I/O pins must be connected to a properly terminated line or bus.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	−55	+125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	0	500	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				25°C to −55°C	≤85°C	≤125°C	
V_{IH}	Minimum High-Level Input Voltage	V_{out} = 0.1 V or V_{CC} − 0.1 V $\|I_{out}\|$ ≤ 20 μA	4.5 5.5	2.0 2.0	2.0 2.0	2.0 2.0	V
V_{IL}	Maximum Low-Level Input Voltage	V_{out} = 0.1 V or V_{CC} − 0.1 V $\|I_{out}\|$ ≤ 20 μA	4.5 5.5	0.8 0.8	0.8 0.8	0.8 0.8	V
V_{OH}	Minimum High-Level Output Voltage	V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 20 μA	4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
		V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 6.0 mA	4.5	3.98	3.84	3.70	
V_{OL}	Maximum Low-Level Output Voltage	V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 20 μA	4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		V_{in} = V_{IH} or V_{IL} $\|I_{out}\|$ ≤ 6.0 mA	4.5	0.26	0.33	0.40	
I_{in}	Maximum Input Leakage Current	V_{in} = V_{CC} or GND, Pin 1 or 19	5.5	±0.1	±1.0	±1.0	μA
I_{OZ}	Maximum Three-State Leakage Current	Output in High-Impedance State V_{in} = V_{IL} or V_{IH} V_{out} = V_{CC} or GND, I/O Pins	5.5	±0.5	±5.0	±10.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	V_{in} = V_{CC} or GND I_{out} = 0 μA	5.5	8	80	160	μA

				≥ −55°C	25°C to 125°C	
ΔI_{CC}	Additional Quiescent Supply Current	V_{in} = 2.4 V, Any One Input V_{in} = V_{CC} or GND, Other Inputs I_{out} = 0 μA	5.5	2.9	2.4	mA

NOTES:
1. Information on typical parametric values can be found in Chapter 4.
2. Total Supply Current = I_{CC} + $\Sigma\Delta I_{CC}$.

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AC ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 V ± 10%, C_L = 50 pF, Input $t_r = t_f$ = 6 ns)

Symbol	Parameter	Guaranteed Limit			Unit
		25°C to −55°C	≤85°C	≤125°C	
t_{PLH}, t_{PHL}	Maximum Propagation Delay, A to B or B to A (Figures 1 and 3)	26	33	39	ns
t_{PLZ}, t_{PHZ}	Maximum Propagation Delay, Direction or Output Enable to A or B (Figures 2 and 4)	35	44	52	ns
t_{PZL}, t_{PZH}	Maximum Propagation Delay, Direction or Output Enable to A or B (Figures 2 and 4)	46	58	69	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 3)	12	15	18	ns
C_{in}	Maximum Input Capacitance (Pin 1 or 19)	10	10	10	pF
C_{out}	Maximum Three-State I/O Capacitance (I/O in High-Impedance State)	15	15	15	pF

NOTES:
1. For propagation delays with loads other than 50 pF, see Chapter 4.
2. Information on typical parametric values can be found in Chapter 4.

C_{PD}	Power Dissipation Capacitance (Per Transceiver Channel) Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ For load considerations, see Chapter 4.	Typical @ 25°C, V_{CC} = 5.0 V 45	pF

SWITCHING WAVEFORMS

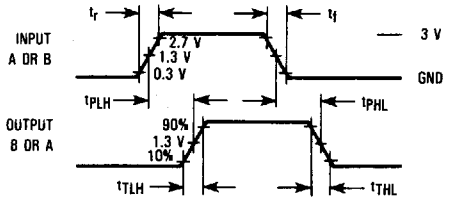


Figure 1.

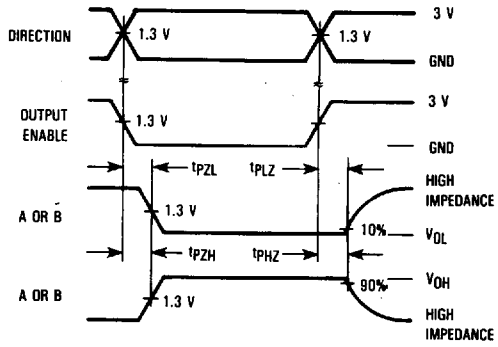
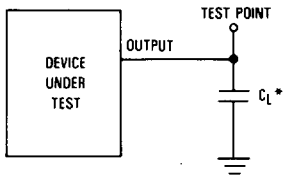


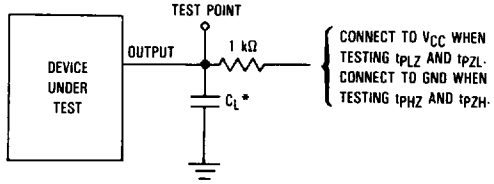
Figure 2.

TEST CIRCUITS



*Includes all probe and jig capacitance.

Figure 3.



*Includes all probe and jig capacitance.

Figure 4.

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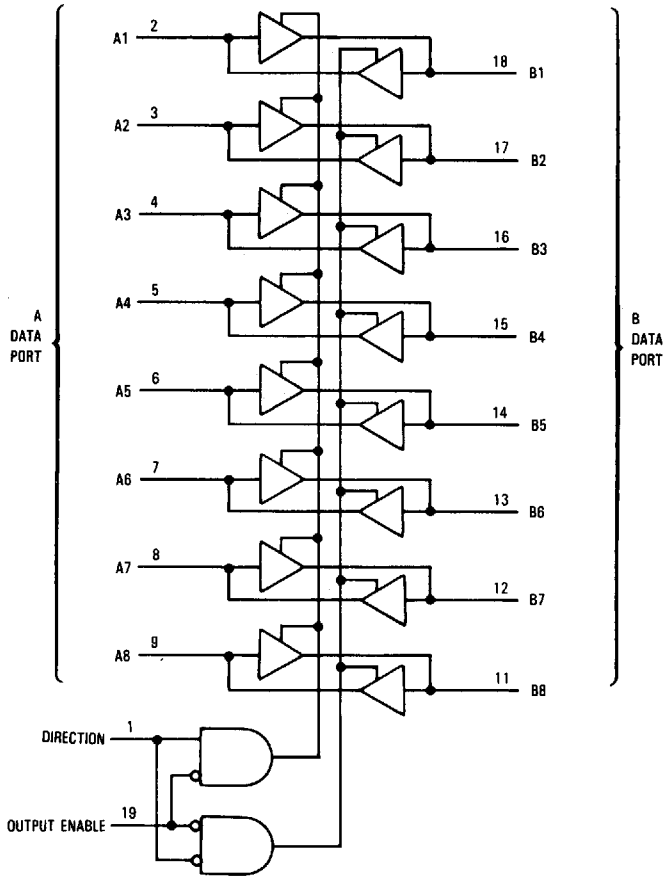
EXPANDED LOGIC DIAGRAM



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